

# EUROPEAN PATENT OFFICE

## Patent Abstracts of Japan

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APPLICANT : MATSUSHITA ELECTRIC WORKS LTD;

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TITLE : SEALING EPOXY RESIN MOLDING MATERIAL

ABSTRACT : PURPOSE: To solve low stress properties compatible with moldability which have been problems in sealing epoxy resin molding materials for sealing and molding electrical and electronic parts in which the low stress properties are required.

CONSTITUTION: Improvements in low stress and moldability can be attained by providing a sealing epoxy resin molding material containing a reaction product of an organopolysiloxane with a phenolic resin and/or an organopolysiloxane rubber powder having the surface treated with a silane or a silicone oil.

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